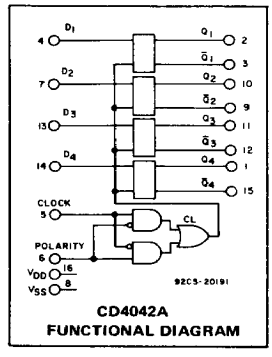
CMOS Quad Clocked "D" Latch

The RCA-CD4042A types contain four latch circuits, each strobed by a common clock. Complementary buffered outputs are available from each circuit. The impedance of the n- and p-channel output devices is balanced and all outputs are electrically identical.

Information present at the data input is transferred to outputs Q and $\overline{Q}$ during the CLOCK level which is programmed by the POLARITY input. For POLARITY = 0 the transfer occurs during the 0 CLOCK level and for POLARITY = 1 the transfer occurs during the 1 CLOCK level. The outputs follow the data input providing the CLOCK and POLARITY levels defined above are present. When a CLOCK transition occurs (positive for POLARITY = 0 and negative for POLARITY = 1) the information present at the input during the CLOCK transition is retained at the outputs until an opposite CLOCK transition occurs.

These types are supplied in 16-lead hermetic dual-in-line ceramic packages (D and F suffixes), 16-lead dual-in-line plastic package (E suffix), 16-lead ceramic flat package (K suffix), and in chip form (H suffix).



CD4042A
FUNCTIONAL DIAGRAM

MAXIMUM RATINGS, *Absolute-Maximum Values:*

STORAGE-TEMPERATURE RANGE (T_{stg}) . . . . . −65 to +150°C
OPERATING-TEMPERATURE RANGE (T_A):
PACKAGE TYPES D, F, K, H . . . . . −55 to +125°C
PACKAGE TYPE E . . . . . −40 to +85°C
DC SUPPLY-VOLTAGE RANGE, (V_{DD})
(Voltages referenced to V_{SS} Terminal): . . . . . −0.5 to +15 V
POWER DISSIPATION PER PACKAGE (P_D):
FOR T_A = −40 to +60°C (PACKAGE TYPE E) . . . . . 500 mW
FOR T_A = +60 to +85°C (PACKAGE TYPE E) . . . . . Derate Linearly at 12 mW/°C to 200 mW
FOR T_A = -55 to +100°C (PACKAGE TYPES D, F, K) . . . . . 500 mW
FOR T_A = +100 to +125°C (PACKAGE TYPES D, F, K) . . . Derate Linearly at 12 mW/°C to 200 mW
DEVICE DISSIPATION PER OUTPUT TRANSISTOR
FOR T_A = FULL PACKAGE-TEMPERATURE RANGE (ALL PACKAGE TYPES) . . . . . 100 mW
INPUT VOLTAGE RANGE, ALL INPUTS . . . . . −0.5 to V_{DD} +0.5 V
LEAD TEMPERATURE (DURING SOLDERING):
At distance 1/16 ±1/32 inch (1.59 ±0.79 mm) from case for 10 s max . . . . . +265°C

DYNAMIC ELECTRICAL CHARACTERISTICS at T_A = 25°C, Input t_r, t_f = 20 ns, C_L = 15 pF, R_L = 200 KΩ

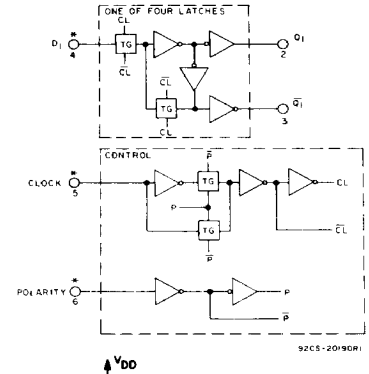
CHARACTERISTIC	V_{DD} (V)	LIMITS				UNITS
		D, F, K, H Packages		*E Package*		
		Typ.	Max.	Typ.	Max.	
Propagation Delay Time: t_{PHL}, t_{PLH} Data In to Q	5	150	300	150	400	ns
	10	75	150	75	200	
Data In to $\overline{Q}$	5	250	500	250	600	ns
	10	100	200	100	250	
Clock to Q	5	300	600	300	750	ns
	10	125	250	125	300	
Clock to $\overline{Q}$	5	400	800	400	1000	ns
	10	175	350	175	400	
Transition Time: t_{THL}, t_{TLH}	5	100	200	100	300	ns
	10	50	100	50	150	
Minimum Clock Pulse Width, t_W	5	175	250	175	350	ns
	10	60	120	60	175	
Minimum Hold Time, t_H	5	150	300	150	350	ns
	10	60	120	60	150	
Minimum Setup Time, t_S	5	0	50	0	50	ns
	10	0	30	0	30	
Minimum Clock Rise or Fall Time: t_r, t_f	5	Not rise or fall time sensitive.				μs
	10					
Input Capacitance, C_I (Any Input)	—	5	—	5	—	pF

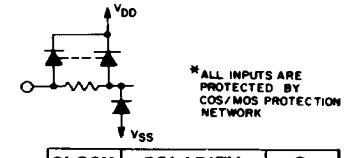
Features:

- **Clock polarity control**
- **Q and $\overline{Q}$ outputs**
- **Common clock**
- **Low power TTL compatible**
- **Quiescent current specified to 15 V**
- **Maximum input leakage of 1 μA at 15 V (full package-temperature range)**
- **1-V noise margin (full package-temperature range)**

Applications:

- **Buffer storage**
- **Holding register**
- **General digital logic**





CLOCK	POLARITY	Q
0	0	D
⌐	0	LATCH
1	1	D
⌙	1	LATCH

Fig. 1 — Logic block diagram & truth table.

RECOMMENDED OPERATING CONDITIONS at T_A = 25°C, Except as Noted.
For maximum reliability, nominal operating conditions should be selected so that operation is always within the following ranges:

CHARACTERISTIC	V_{DD} (V)	LIMITS				UNITS
		D, F, K, H Packages		*E Package*		
		Min.	Max.	Min.	Max.	
Supply-Voltage Range (For T_A = Full Package Temperature Range)	–	3	12	3	12	V
Clock Pulse Width, t_W	5 10	350 175	– –	250 120	– –	ns
Setup Time, t_S	5 10	50 30	– –	50 30	– –	ns
Hold Time, t_H	5 10	350 150	– –	300 120	– –	ns
Clock Rise or Fall Time: t_r, t_f	5 10	Not rise or fall time sensitive.				μs

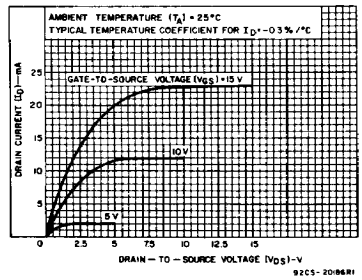


Fig. 2 – Typical output n-channel drain characteristics.

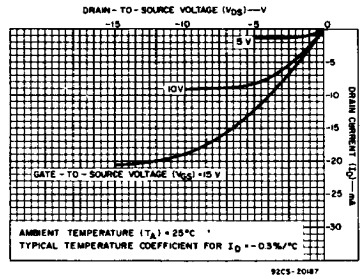


Fig. 3 – Typical output p-channel drain characteristics.

STATIC ELECTRICAL CHARACTERISTICS

Characteristic	Conditions			Limits at Indicated Temperatures (°C)								Units
				D, F, K, H Packages				*E Package*				
	V_O (V)	V_{IN} (V)	V_{DD} (V)	–55	+25 Typ.	+25 Limit	+125	–40	+25 Typ.	+25 Limit	+85	
Quiescent Device Current, I_L Max.	–	–	5	1	0.005	1	60	10	0.01	10	140	μA
	–	–	10	2	0.005	2	120	20	0.02	20	280	
	–	–	15	25	0.25	25	1000	250	2.5	250	2500	
Output Voltage: Low-Level, V_{OL}	–	0,5	5	0 Typ.; 0.05 Max.								V
	–	0,10	10	0 Typ.; 0.05 Max.								
High Level, V_{OH}	–	0,5	5	4.95 Min.; 5 Typ.								
	–	0,10	10	9.95 Min.; 10 Typ.								
Noise Immunity: Inputs Low, V_{NL}	4.2	–	5	1.5 Min.; 2.25 Typ.								V
	9	–	10	3 Min.; 4.5 Typ.								
Inputs High, V_{NH}	0.8	–	5	1.5 Min.; 2.25 Typ.								
	1	–	10	3 Min.; 4.5 Typ.								
Noise Margin: Inputs Low, V_{NML}	4.5	–	5	1 Min.								V
	9	–	10	1 Min.								
Inputs High, V_{NMH}	0.5	–	5	1 Min.								
	1	–	10	1 Min.								
Output Drive Current: n-Channel (Sink), I_DN Min.	0.5	–	5	0.5	1	0.4	0.27	0.24	1	0.2	0.18	mA
	0.5	–	10	1.25	2	1	0.7	0.6	2	0.5	0.45	
p-Channel (Source), I_DP Min.	4.5	–	5	-0.45	-1	-0.35	-0.25	-0.2	-1	-0.175	-0.15	
	9.5	–	10	-1.15	-2	-0.9	-0.6	-0.34	-2	-0.45	-0.4	
Input Leakage Current, I_{IL}, I_{IH} Max.	Any Input		15	$\pm 10^{-5}$ Typ.; 1 Max.								μA

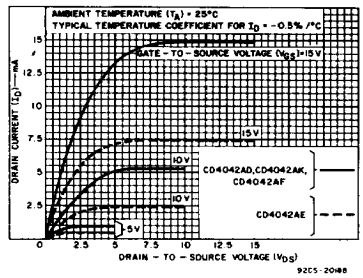


Fig. 4 – Minimum n-channel drain characteristics.

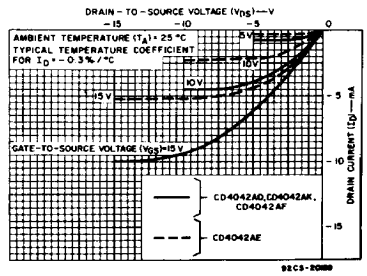
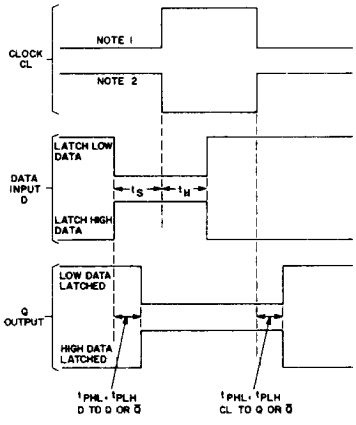


Fig. 5 – Minimum p-channel drain characteristics.



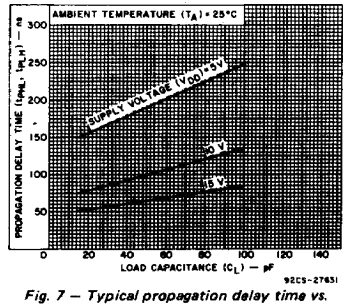


Fig. 7 – Typical propagation delay time vs. load capacitance– data to Q.

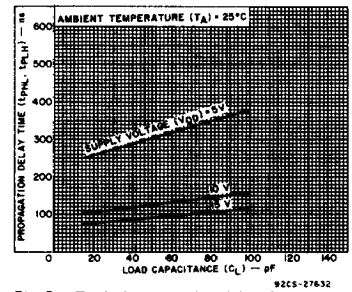


Fig. 8 – Typical propagation delay time vs. load capacitance – data to $\overline{Q}$.

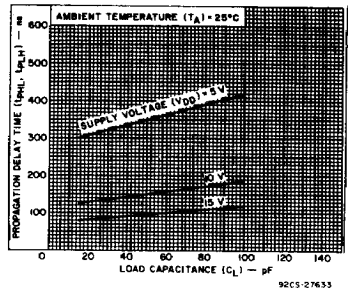


Fig. 9 – Typical propagation delay time vs. load capacitance – clock to Q.

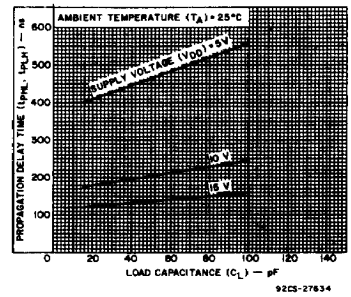


Fig. 10 – Typical propagation delay time vs. load capacitance – clock to $\overline{Q}$.

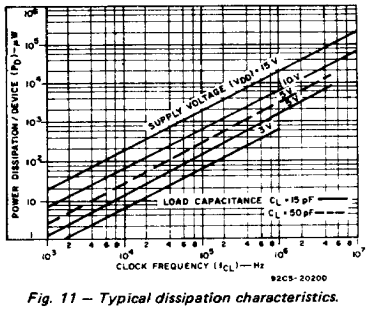


Fig. 11 – Typical dissipation characteristics.

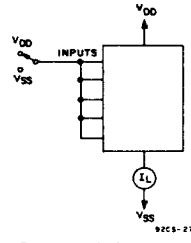


Fig. 12 – Quiescent device current test circuit.

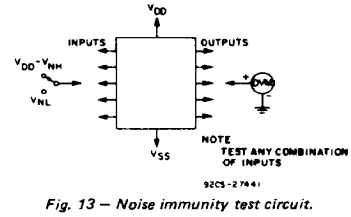


Fig. 13 – Noise immunity test circuit.

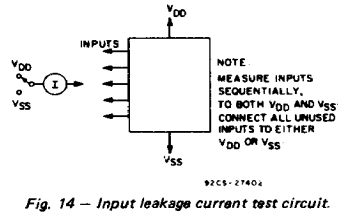


Fig. 14 – Input leakage current test circuit.